

USB Type-A fast charging protocol intelligent management chip

Product Features

- Compatible with common USB Type-A fast charging protocols, BC1.2 , Apple 2.4A, QC2.0/QC3.0/QC3.0+, FCP, SCP, HISCP, Low voltage direct charging, etc.
- Support dynamic shutdown of fast charging output
- VIN withstand voltage 36V, D ± withstand voltage 22V
- Internal integration of LDO
- Internal integrated FB voltage divider resistor
- Package: SOT23-6

Product Overview

The FS158K (abbreviated as FSFA series) chip is selectively compatible with mainstream charging protocols. The chip can intelligently recognize the type of phone inserted and select the most suitable protocol to meet the needs of the phone.

The D ± of the USB Type-A port is connected to the FSFA chip. After the phone is inserted into the USB Type-A port, according to the agreements of various protocols, the phone and FSFA will start to recognize each other. Once the recognition is successful, FSFA can respond to the phone's request.

The VIN withstand voltage of FS158K is as high as 36V, and the D ± withstand voltage is as high as 22V, which improves the reliability of the system.

Internally integrated with LDO, low loss during high-voltage output, chip power supply can be directly connected to the power supply.

FS158K uses SOT23-6 packaging.

Application field

- Travel Charge
- Wall filling
- Socket
- Other USB Type-A power output devices

Order information

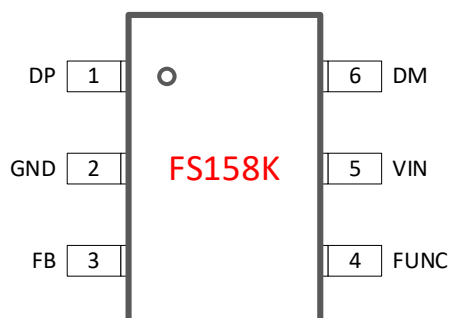
Part No	Package	Pcs/Reel
FS158KA	SOT23-6	3000
FS158KC	SOT23-6	3000
FS158KD	SOT23-6	3000
FS158KE	SOT23-6	3000

Note: Please refer to the "Device Selection" section for details

V1.2(202511)



Chip packaging and pin definition



SOT23-6

Pic 1. Pin definition

Table 1. FS158K Pin function description

FS158K	Name of the pin	Description
1	DP	USB DP, DP connected to USB Type-A port
2	GND	Chip ground, connected to system ground
3	FB	FB feedback, connecting to the VFB of the DC-DC
4	FUNC	Enable fast charging Suspended: maximum 13.2V 180K: Maximum 20V 68K: Maximum 10.2V Grounding: Shielded fast charging
5	VIN	Chip power supply
6	DM	USB DM, DM connected to USB Type-A port



Extreme operating range

Table 2. Maximum operating range

Parameter	Value
VIN	-0.3V~36V
D±	-0.3V~22V
FUNC	-0.3V~8V
ESD (HBM)	±2KV

The maximum operating range listed in the table above, if the limit is exceeded, the chip may be permanently damaged. Users should try to avoid it.

Normal operating range

Table 3. Normal operating range

Parameter	Value
VIN	2.9V~20V
D±	0V~3.3V
FUNC	0V~3.3V
Working temperature range	-40°~105°
Working current	<2mA

Device Configuration

The identification method for the FS158K series is FS158KX.

X represents compatible protocols, commonly defined in the table below.

Table 4. Named X Values

X value	Agreement
A	BC1.2APPLE2.4A, QC2.0/QC3.0/QC3.0+, AFC, FCP
C	BC1.2APPLE2.4A, QC2.0/QC3.0/QC3.0+, AFC, FCP, V, SCP, HISCP, Low-voltage direct charging
D	BC1.2APPLE2.4A, QC2.0/QC3.0/QC3.0+, AFC, FCP, V, SCP, HISCP, High-voltage direct charging, others
E	BC1.2APPLE2.4A, QC2.0/QC3.0/QC3.0+, AFC, FCP, V, SCP, HISCP, High-voltage direct charging, T-ECNO, others



Pin definition and instructions

VIN

The voltage resistance of VIN can reach up to 36V and can be directly connected to the power system. VIN requires an external capacitor to ensure strong and stable power supply. A 1uF capacitor is recommended.

DP and DM

DP/M is connected to the USB Type-A port, and both pins can withstand a voltage of 22V.

FUNC

Suspended: maximum 13.2V

180K: Maximum 20V

68K: Maximum 10.2V

Grounding: Shielded fast charging

FB

The internal integrated feedback resistors eliminate the need for users to externally connect pull-up and pull-down resistors. By default, VFB = 1V.

If the VFB value of the used DC-DC is lower than 1V, external pull-up and pull-down resistors need to be connected; please contact our company for specific wiring.



Application example

The typical application of FS158K is shown in the figure on the right.
FB connects to DCDC's FB, note that a power chip with $V_{FB}=1V$ is needed.

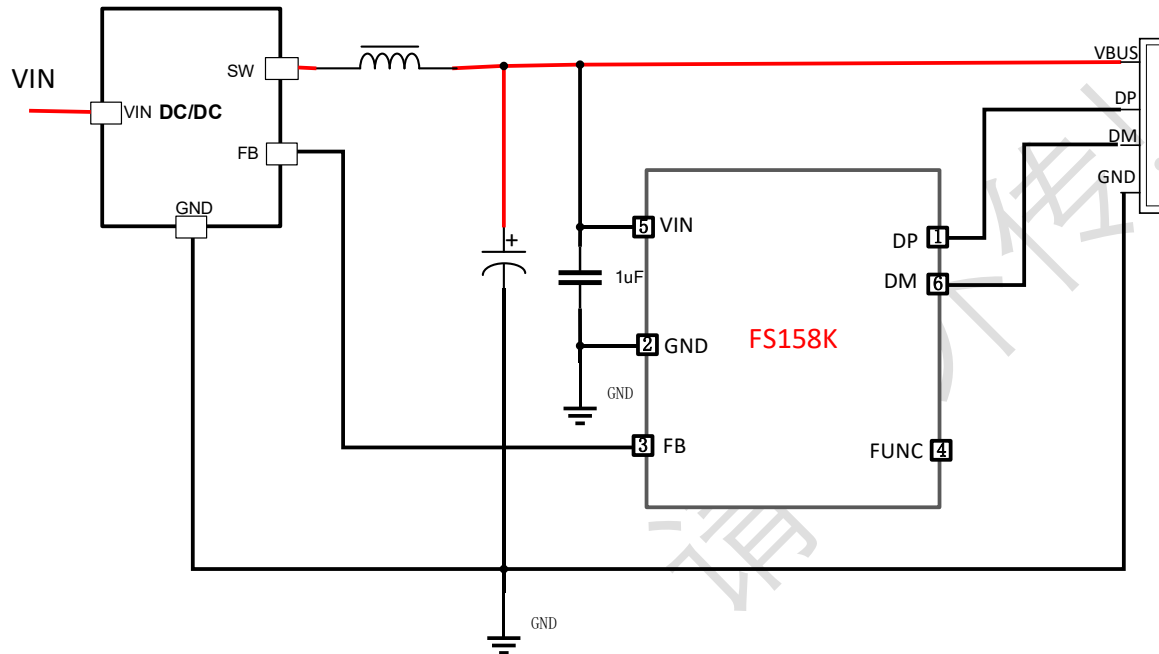
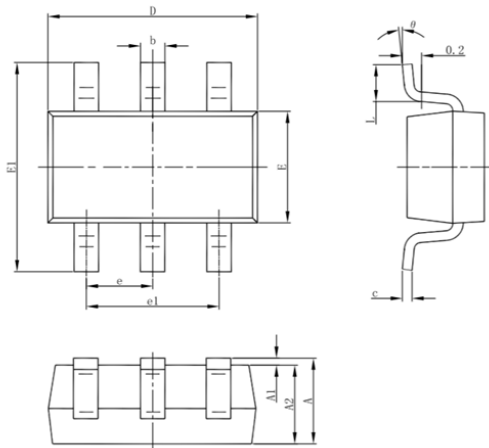


Figure 2. Application diagram



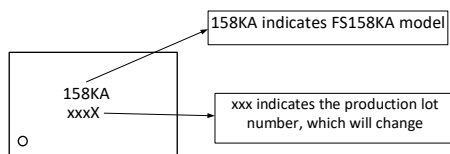
Package outline drawing

SOT23-6

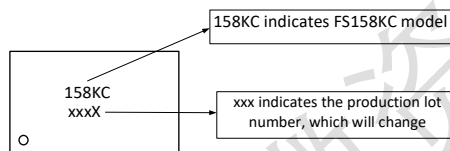


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

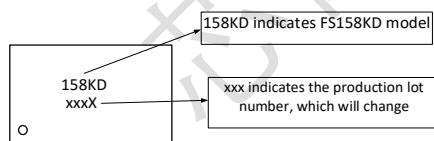
Chip silk screen information



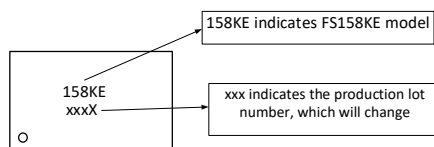
FS158KA model information: 158KA, fixed; The production batch number shortcode is to distinguish the batch number information each time, and it varies according to the production batch



FS158KC model information: 158KC, fixed; The production batch number shortcode is to distinguish the batch number information each time, and it varies according to the production batch



FS158KD model information: 158KD, fixed; The production batch number shortcode is to distinguish the batch number information each time, and it varies according to the production batch



FS158KE model information: 158KE, fixed; The production batch number shortcode is to distinguish the batch number information each time, and it varies according to the production batch



Company information and statement

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